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Assistant Commissioner for Patents  
Washington, D.C. 20231


**CERTIFICATE OF MAILING BY "EXPRESS MAIL"**

**Docket No.** : JCLA8534  
**Inventor(s)** : JIN-YUAN LEE ;  
MOU-SHIUNG LIN;  
CHING-CHENG HUANG  
**For** : INTEGRATED CHIP PACKAGE STRUCTURE USING  
ORGANIC SUBSTRATE AND METHOD OF  
MANUFACTURING THE SAME  
**"Express Mail"**  
**Mailing Label No.** : EV 016848593 US  
**Date of Deposit** : January 22, 2002

I hereby certify that the accompanying

Transmittal in Duplicate; Specification in 66 page(s); 17 Pages of Drawings;  
**SIGNED** Declaration and Power of Attorney in 2 page(s); Assignment and  
Recordation Cover Sheet in 3 pages; Checks for Filing Fee(s); Return Prepaid  
Postcard

are being deposited with the United States Postal Service "Express Mail Post Office to Addressee"  
service under 37 CFR 1.10 on the date indicated above and are addressed to the Assistant  
Commissioner for Patents, Washington, D.C. 20231.

  
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Michelle Chang